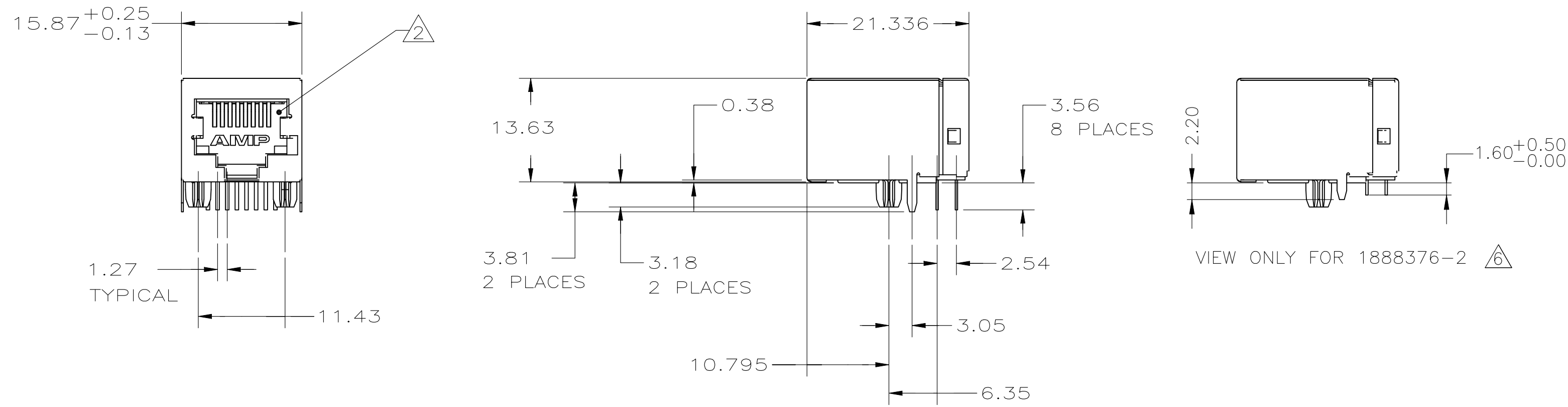
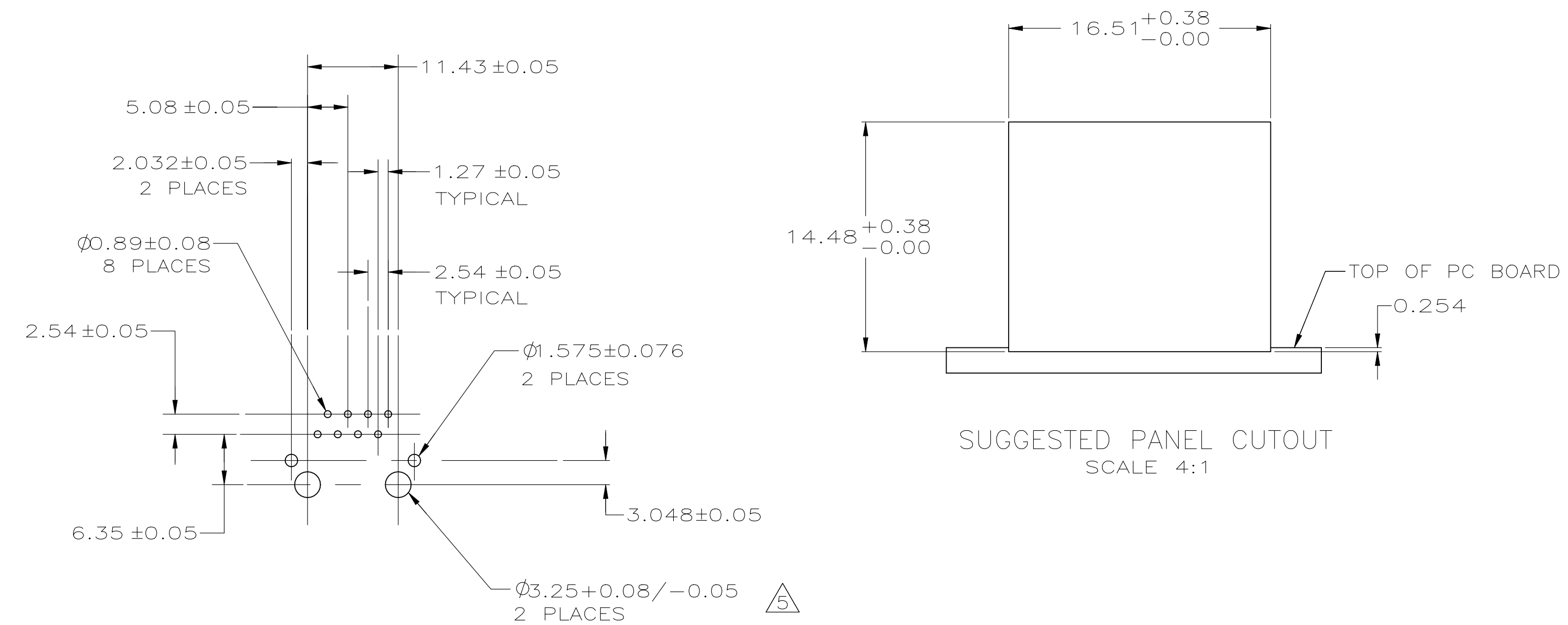
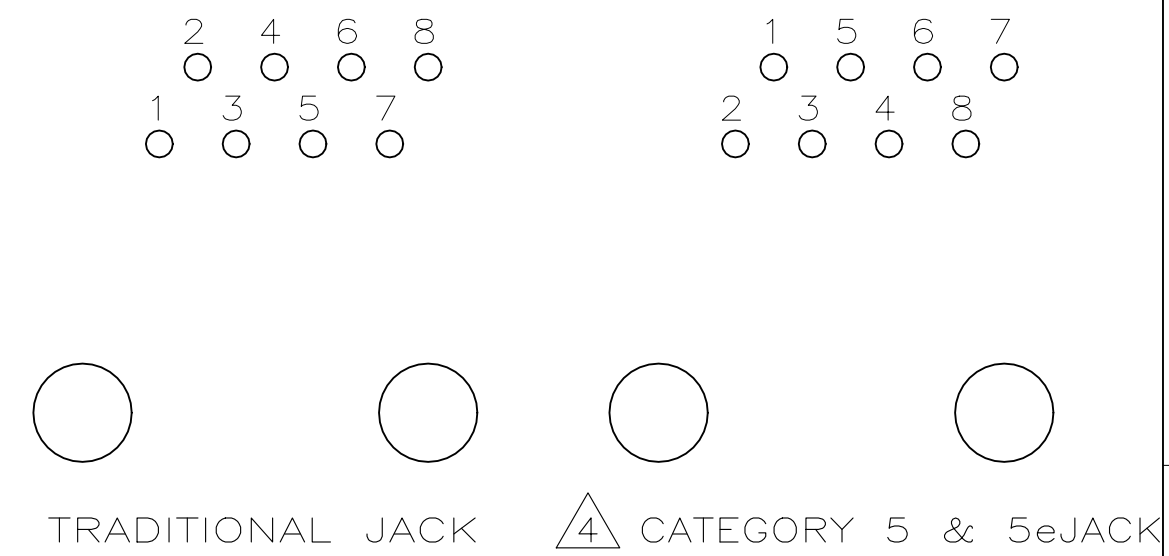


REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	C1	ECR-19-014657	13DEC2020	RR	SZ

-  MATERIAL: HOUSING HIGH TEMPERATURE NYLON, TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81µm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MINIMUM THICK NICKEL UNDERPLATE.
SHIELDS - 0.254[.010] THICK COPPER ALLOY PLATED WITH 1.27 µm [.000050] MINIMUM SATIN NICKEL WITH 2.03 µm [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS
-  JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
3. ALL DIMENSIONS SHOWN ARE NOMINAL UNLESS OTHERWISE SPECIFIED.
-  CAUTION: CATEGORY 5 JACK SOLDER TAIL POSITIONS DO NOT FOLLOW SAME NUMBER SEQUENCE AS THAT OF TRADITIONAL JACKS.
-  USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.
-  SHORT PIN TYPE, ONLY FOR 1888376-2
-  MATERIAL: LCP, BLACK, UL94V-0. LEAD FREE IR REFLOW PROCESS COMPATIBLE.
TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81µm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MINIMUM THICK NICKEL UNDERPLATE.
SHIELDS - 0.254[.010] THICK COPPER ALLOY PLATED WITH 1.27 µm [.000050] MINIMUM SATIN NICKEL WITH 2.03 µm [.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS



SUGGESTED PANEL CUTOUT
SCALE 4:1



	TAPE&REEL	 1888376-2
	TRAY	1888376-1
MATERIAL	PACKAGE	PART NUMBER

SUGGESTED PC BOARD LAYOUT
COMPONENT SIDE

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN T. PITTS/L.A.MAYER 01JUNE2005	 TE Connectivity		
		CHK J.WESTMAN 01JUNE2005			
		APVD S.FLICKINGER 01JUNE2005	NAME		
		PRODUCT SPEC	MODULAR JACK ASSY, 8 POS, R/A,LOW PROFILE,SHIELDED, PC BOARD GROUND,CATEGORY 5e		
		APPLICATION SPEC			
		114-2048			
MATERIAL		FINISH	WEIGHT	SCALE	REV
SEE NOTE 1 & 8		SEE NOTE 1 & 8	-	2:1	C1
		CUSTOMER DRAWING			